

CALL FOR PARTICIPATION

10th IEEE WORKSHOP ON

SIGNAL PROPAGATION ON INTERCONNECTS

Sponsored by the IEEE Components, Packaging, and Manufacturing Technology (CPMT) Society and by the IEEE Computer Society – Test Technology Technical Council (TTTC)

May 09-12, 2006 "Dorint Sofitel Schweizerhof Berlin", Berlin-Mitte, Germany

During the last nine years, the IEEE Workshop on Signal Propagation on Interconnects has been developed into a forum of exchange on the latest research results in this area. The aim of this ensuing workshop is to report on the most recent developments in the field of interconnect modeling, simulation and measurement on chips, boards, and packages. The event is also meant to bring together developers and researchers from industry and academia in order to encourage co-operation. In view of the last years' success, the committee is looking forward to the 10th IEEE Workshop on Signal Propagation on Interconnects where world class developers and researchers will share and discuss leading-edge results in the famous and historic city of Berlin, Germany. The social events bundle takes care you'll never forget where you learned about the latest news on interconnects and testing: we are going to have a guided sightseeing tour through Germany's capital city followed by an excellent dinner. The workshop will be held in English. We are looking forward to see you in Berlin.

Main topics of the workshop will include, but are not limited to:

- * Frequency Domain Measurement Techniques
- * Modeling of Package & On-Chip Interconnects
- * Simulation of Interconnect Structures
- * Analysis and Modeling of Power Distribution Networks
- * Propagation Characteristics on Transmission Lines
- * Substrate Effects
- * Electromagnetic Compatibility
- * Testing & Interconnects
- * Time Domain Measurement Techniques
- * Macro-Modeling
- * Electromagnetic Field Theory
- * Guided Waves on Interconnects
- * Coupling Effects on Interconnects
- * Radiation & Interference
- * Power/Ground-Noise
- * Optical Interconnects

Advance Program and registration information now posted on the website: www.spi.uni-hannover.de

ITherm 2006

InterSociety Conference on Thermal Phenomena in Electronic Systems
May 30 - June 2, 2006 San Diego, CA, USA

ITherm 2006 is an international conference for scientific and engineering exploration of thermal, thermomechanical and emerging technology issues associated with electronic devices, packages and systems. It is held simultaneously with the 56th Electronic Components and Technology Conference. One unique feature for **ITherm 2006** is that one entire afternoon session will be dedicated to the Poster Presentations along with the Vendor Exhibits. In addition to paper and poster presentations and vendor exhibits, **ITherm 2006** includes panel discussions, keynote lectures by prominent speakers, and professional short courses.

ITherm 2006 features original papers addressing the latest developments in research and technology

Thermal Management	Mechanics	Materials
Emerging Technologies: Thermal, Thermomechanical and/or related underlying multidisciplinary issues		
Software Tools & Techniques: Design, Analysis, Simulation		
Panel Discussions	Poster Sessions	

Oral and poster presentations will be featured. The first day of the conference has a series of short courses. Several keynote speeches on topics of current importance by experts in the field will be part of the conference program.

Download the full program and registration information: www.itherm.org